

### ABSTRACT

A polyimide metal laminate comprising a polyimide resin formed on a metal foil, wherein the polyimide resin does not cause the peeling of not less than 100  $\mu\text{m}$  in the polyimide resin and/or at an interface between the polyimide resin and the metal foil when the polyimide resin is heated in an oven at an atmospheric temperature of from 340 to 360°C for 5 to 10 minutes, the coefficient of humidity expansion at 32° is from 1 to 20 ppm/%RH, and an average value of the etching rate by a 50 wt % aqueous solution of potassium hydroxide at 80°C is not less than 1.0  $\mu\text{m}/\text{min}$ . The polyimide metal laminate can provide good heat resistance, superior dimensional stability and can be etching processed by an aqueous alkaline solution.